

PCN# 20210202000.1<mark>A</mark> Qualification of RFAB as an additional Fab site option for select devices and Datasheet Update Change Notification / Sample Request

Date:July 14, 2022To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

PCN Revision A is to announce the <u>retraction</u> of select devices.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative.

PCN Team SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE

CUSTOMER PART NUMBER

TPS62143RGTR TPS62133RGTT TPS62133RGTR null null null

Technical details of this Product Change follow on the next page(s).

PCN Number:	2021020	10202000.1 <mark>A</mark> P			Date:	July 14, 2022	
Title: Qualification of RFAB as an additional Fab site option for select devices and Datashee Update Update					vices and Datasheet		
Customer Contact:	PCN	<u>Manager</u>		Dept:		Quality Services	
Proposed 1 st Ship Date: May		y 2, 2021	Estimated Sample Availability:		ample	Not Applicable	
Change Type:							
Assembly Site		Assembly Process	S		Assembly Materials		
Design	\square	Electrical Specification			Mechanical Specification		
Test Site		Packing/Shipping/Labelin			Test Process		
Wafer Bump Site		Wafer Bump Material			Wafer Bump Process		
Wafer Fab Site	\square	Wafer Fab Materials			Wafer	Fab Process	
		Part number change					

Notification Details

Description of Change:

The purpose of **PCN Revision A** is to announce the <u>retraction</u> of select devices. Retracted devices are identified with a strikethrough and are highlighted in yellow in the Product Affected Section. Retracted devices are no longer impacted by this PCN.

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site			
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter	
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm	

As part of the RFAB qualification, it was determined that the previous Datasheet limits were not accurate (this is also true for MIHO8). This has been corrected and the datasheet number will be changing as shown below:

Device Family	Change From:	Change To:
TPS62085	SLVSB70B	SLVSB70C
BQ24040, BQ24041, BQ24045	SLUS941G	SLUS941H

TPS62085, TPS62086, TPS62087

SLVSB70C - OCTOBER 2013 - REVISED JANUARY 2021



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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision B (July 2018) to Revision C (January 2021)



BQ24040, BQ24041, BQ24045 SLUS941H – SEPTEMBER 2009 – REVISED FEBRUARY 2021

Changes from Revision G (June 2020) to Revision H (February 2021)	Page
Added BQ24040, BQ24045 to IEC 62368-1 CB Certification Feature	
Changed I _{BD-SINK} minimum from 7 mA to 6 mA	7
 Changed I_{IH} maximum from 8 μA to 9.5 μA 	7

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TPS62085

http://www.ti.com/product/BQ24040

Reason for Change:

Continuity of supply and to accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): None.

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)



Product Affected:

Group 1: Adding RFAB as an additional site					
BQ24050DSQR	SN1809004RHLT	TPS54622RHLR	TPS62140RGTT		
BQ24050DSQT	SN54622RHLR	TPS54622RHLT	TPS62141RGTR		
BQ24052DSQR	SN62085RLTR	TPS546C20RVFR	TPS62141RGTT		
BQ24052DSQT	SN62130ARGTR	TPS546C20RVFT	TPS62142RGTR		
BQ24090DGQR	SN62130ARGTT	TPS62130AGRGTR	TPS62142RGTT		
BQ24090DGQT	TLV62085RLTR	TPS62130AGRGTT	TPS62143RGTR		
BQ24091DGQR	TLV62085RLTT	TPS62130ARGTR	TPS62143RGTT		
BQ24091DGQT	TLV62130ARGTR	TPS62130ARGTT	TPS62150ARGTR		
BQ24092DGQR	TLV62130ARGTT	TPS62130GRGTR	TPS62150ARGTT		
BQ24092DGQT	TLV62130RGTR	TPS62130GRGTT	TPS62150BRGTR		
BQ24093DGQR	TLV62130RGTT	TPS62130RGTR	TPS62150RGTR		
BQ24093DGQT	TLV62150ARGTR	TPS62130RGTRF0	TPS62150RGTRF0		
BQ24095DGQR	TLV62150ARGTT	TPS62130RGTT	TPS62150RGTT		
BQ24095DGQT	TLV62150RGTR	TPS62131RGTR	TPS62151RGTR		
SN1208058RHLR	TLV62150RGTT	TPS62132RGTR	TPS62151RGTT		
SN1210015RHLR	TPS2553DBVR	TPS62132RGTT	TPS62152RGTR		

SN1409057DBVR	TPS2553DBVT	TPS62133RGTR	TPS62152RGTT		
SN1610044RHLR	TPS2553DDBVR	TPS62133RGTT	TPS62153RGTR		
SN1703013RHLR	TPS2553DDBVT	TPS62140RGTR	TPS62153RGTT		
SN1809004RHLR					
	-				
Group 2: Adding RFAB and Datasheet update					
BQ24040DSQR	BQ24041DSQT	SN2040DSQR	TPS62085RLTT		

Qualification Report

SN2040DSQT

TPS62085RLTR

BQ24045DSQR

BQ24045DSQT

Approve Date 28-December-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: BQ24095DGQR	Qual Device: SN1703013RHLR	Qual Device: TP \$2553DBVR	Qual Device: TP \$546C20RVFR	Qual Device: TP \$62085RLTR	Qual Device: TP \$62130ARGTR	QBS Process Reference: TP S3703C7500DSERQ1
HTOL	Life Test, 125C	1000 Hours	-	-	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	-	-	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	-	-	-	-	-	-	3/231/0
HBM	ESD - HBM	V	1/3/0 (3000V)	1/3/0 (2000V)	1/3/0 (2000V)	1/3/0 (2000V)	1/3/0 (2000V)	1/3/0 (2000V)	1/3/0
CDM	ESD - CDM	V	1/3/0 (1500V)	1/3/0 (500V)	1/3/0 (500V)	1/3/0 (500V)	1/3/0 (500V)	1/3/0 (500V)	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0
ED	Electrical Distributions	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	3/90/0
MQ	Assembly MQ	per mfg. Site specification	Pass	Pass	Pass	Pass	Pass	Pass	Pass
WBP	Bond Pull	Wires	1/80/0	1/80/0	1/80/0	1/80/0	1/80/0	1/80/0	3/240/0
WBS	Bond Shear	Wires	1/80/0	1/80/0	1/80/0	1/80/0	1/80/0	1/80/0	3/240/0

- QBS: Qual By Similarity

BQ24040DSQT

BQ24041DSQR

- Qual Device BQ24095DGQR is qualified at LEVEL1-260C

- Qual Device SN1703013RHLR is qualified at LEVEL2-260C

- Qual Device TPS2553DBVR is qualified at LEVEL1-260C

- Qual Device TPS546C20RVFR is gualified at LEVEL2-260C

- Qual Device TPS62085RLTR is gualified at LEVEL1-260C

- Qual Device TPS62130ARGTR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	PCN_ww_admin_team@list.ti.com

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